

3D TSV and 2.5D Market Report: Trends, Forecast and Competitive Analysis

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Abstracts

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The future of the 3D TSV and 2.5D market looks promising with opportunities in the consumer electronics, automotive, high-performance computing and networking industries. The global 3D TSV and 2.5D market is expected to grow with a CAGR of 32% to 34% from 2020 to 2025. The major drivers for this market are growth of the high performance computing application and expanding scope of data centers and memory devices.

A total of XX figures / charts and XX tables are provided in more than 150 pages report is developed to help in your business decisions. Sample figures with some insights are shown below. To learn the scope, benefits, companies researched, and other details of the global 3D TSV and 2.5D market report, please download the report brochure.

3D TSV and 2.5D

Growth in various segments of the 3D TSV and 2.5D market are given below:

The study includes trends and forecast for the global 3D TSV and 2.5D market by packaging type, end use industry, and region as follows:

By Packaging Type [Value (\$ Million) shipment analysis for 2014 – 2025]:

3D Stacked Memory 2.5D Interposer CIS with TSV3D SoCOthers

By End Use Industry [Value (\$ Million) shipment analysis for 2014 – 2025]:

Consumer ElectronicsAutomotive High-Performance Computing and NetworkingOthers

By Region [Value (\$ Million) shipment analysis for 2014 – 2025]:

North AmericaUnited StatesCanada MexicoEuropeUnited KingdomSpainGermanyFranceAsia PacificChinaIndiaJapanSouth KoreaThe Rest of the World Brazil

Some of the 3D TSV and 2.5D manufacturers profiled in this report include, Taiwan Semiconductor Manufacturing Company, Samsung Electronics, Toshiba, ASE Group, and Amkor Technology.

Lucintel forecasts that CIS with TSV will remain the largest segment over the forecast period due to growth of the smartphones and is increasingly integrated into the high-end market segment for memory devices.

Within this market, consumer electronics is expected to witness the highest growth over the forecast period due to increasing number of smartphones, tablets, and other hand-held devices.

Asia-Pacific will remain the largest region and it is also expected to witness the highest growth over the forecast period due to the increasing smartphone adoption rates have made Asia-Pacific one of the largest mobile markets in the world.

Features of the Global 3D TSV and 2.5D Market

Market Size Estimates: Global 3D TSV and 2.5D market size estimation in terms of value (\$M) shipment.Trend and Forecast Analysis: Market trends (2014-2019) and forecast (2020-2025) by various segments and regions.Segmentation Analysis: Global 3D TSV and 2.5D market size by various segments, such as packaging, end use industry in terms of value.Regional Analysis: Global 3D TSV and 2.5D market breakdown by the North America, Europe, Asia Pacific, and Rest of the World.Growth Opportunities: Analysis of growth opportunities in different packaging, end use industry, and region for the global 3D TSV and 2.5D market.Strategic Analysis: This includes M&A, new product development, and competitive landscape of the global 3D TSV and 2.5D market.Analysis of competitive intensity of the industry based on Porter's Five Forces model.

This report answers following key questions

- Q.1 What are some of the most promising potential, high-growth opportunities for the global 3D TSV and 2.5D market by packaging type (3D stacked memory, 2.5D interposer, CIS with TSV, 3D SoC, and Others), end use industry (consumer electronics, automotive, high-performance computing and networking, and others), and region (North America, Europe, Asia Pacific, and Rest of the World)?
- Q. 2 Which segments will grow at a faster pace and why?
- Q.3 Which region will grow at a faster pace and why?
- Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the market?
- Q.5 What are the business risks and threats to the market?
- Q.6 What are emerging trends in this market and the reasons behind them?
- Q.7 What are some changing demands of customers in the market?
- Q.8 What are the new developments in the market? Which companies are leading these developments?
- Q.9 Who are the major players in this market? What strategic initiatives are being implemented by key players for business growth?
- Q.10 What are some of the competitive products and processes in this market, and how big of a threat do they pose for loss of market share via material or product substitution?
- Q.11 What M & A activities did take place in the last five years in this market?

Contents

1. EXECUTIVE SUMMARY

2. MARKET BACKGROUND AND CLASSIFICATION

2.1: Introduction, Background, and Classification

2.2: Supply Chain

2.3: Industry Drivers and Challenges

3. MARKET TRENDS AND FORECAST ANALYSIS FROM 2014 T 2025

3.1: Macroeconomic Trends and Forecast

3.2: Global 3D TSV and 2.5D Market Trends and Forecast

3.3: Global 3D TSV and 2.5D Market by Packaging Type

3.3.1: 3D Stacked Memory

3.3.2: 5D Interposer

3.3.3: CIS with TSV

3.3.4: 3D SoC

3.3.5: Others

3.4: Global 3D TSV and 2.5D Market by End-user Application

3.4.1: Consumer Electronics

3.4.2: Automotive

3.4.3: High-Performance Computing and Networking

3.4.4: Others

4. MARKET TRENDS AND FORECAST ANALYSIS BY REGION

4.1: Global 3D TSV and 2.5D Market by Region

4.2: North American 3D TSV and 2.5D Market

4.2.1: Market by Packaging Type: 3D Stacked Memory, 2.5D Interposer, CIS with TSV, 3D SoC, and Others

4.2.2: Market by End Use Industry: Consumer Electronics, Automotive, High-Performance Computing and Networking, and Others

4.2.3: United States 3D TSV and 2.5D Market

4.2.4: Canadian 3D TSV and 2.5D Market

4.2.5: Mexican 3D TSV and 2.5D Market

4.3: European 3D TSV and 2.5D Market

4.3.1: Market by Packaging Type: 3D Stacked Memory, 2.5D Interposer, CIS with

TSV, 3D SoC, and Others

4.3.2: Market by End Use Industry: Consumer Electronics, Automotive, High-Performance Computing and Networking, and Others

4.3.3: Germany 3D TSV and 2.5D Market

4.3.4: UK 3D TSV and 2.5D Market

4.3.5: Spain 3D TSV and 2.5D Market

4.3.6: France 3D TSV and 2.5D Market

4.4: APAC 3D TSV and 2.5D Market

4.4.1: Market by Packaging Type: 3D Stacked Memory, 2.5D Interposer, CIS with TSV, 3D SoC, and Others

4.4.2: Market by End Use Industry: Consumer Electronics, Automotive, High-Performance Computing and Networking, and Others

4.4.3: China 3D TSV and 2.5D Market

4.4.4: Japan 3D TSV and 2.5D Market

4.4.5: South Korea 3D TSV and 2.5D Market

4.4.6: India 3D TSV and 2.5D Market

4.5: ROW 3D TSV and 2.5D Market

4.5.1: Market by Packaging Type: 3D Stacked Memory, 2.5D Interposer, CIS with TSV, 3D SoC, and Others

4.5.2: Market by End Use Industry: Consumer Electronics, Automotive, High-Performance Computing and Networking, and Others

4.5.3: Brazil 3D TSV and 2.5D Market

5. COMPETITOR ANALYSIS

5.1: Product Portfolio Analysis

5.2: Market Share Analysis

5.3: Operational Integration

5.4: Geographical Reach

5.5: Porter's Five Forces Analysis

6. GROWTH OPPORTUNITIES AND STRATEGIC ANALYSIS

6.1: Growth Opportunity Analysis

6.1.1: Growth Opportunities for Global 3D TSV and 2.5D Market by Packaging Type

6.1.2: Growth Opportunities for Global 3D TSV and 2.5D Market by End-Use Industry

6.1.3: Growth Opportunities for Global 3D TSV and 2.5D Market by Region

6.2: Emerging Trends in Global 3D TSV and 2.5D Market

6.3: Strategic Analysis

6.3.1: New Product Development

6.3.2: Capacity Expansion of Global 3D TSV and 2.5D Market

6.3.3: Mergers, Acquisitions and Joint Ventures in the Global 3D TSV and 2.5D Market

7. COMPANY PROFILES OF LEADING PLAYERS

7.1: Taiwan Semiconductor Manufacturing Company

7.2: Samsung Electronics

7.3: Toshiba

7.4: ASE Group

7.5: Amkor Technology

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